contact Name  Title - Contact Product-Env-Stewards Product-Enversentative*  Title - Representative  2024-05-21  Email - Contact*  Product-Env-Stewards NA Product-Env-Stewards@onsemi.co Product-Env-Stewards@onsemi.co Product-Env-Stewards@onsemi.co Product-Env-Stewards@onsemi.co Product-Env-Stewards@onsemi.co	PC SOCIATION CONNECTING CTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
Company name*    Company unique ID   Unique ID Authority   Response Date*	2-21.1									ous Materia	als and Mfg	Informati	ion		
Insemi	oplier Informa	ation								, ,					
Title - Contact   Phone - Contact   Phone - Contact   Product Env-Stewards   Product Enviro Compliance   NA   Product-Env-Stewards @ onsemi.co	Company name*				Company unique ID			Unique ID Authority				Response Date*			
Product-Env-Stewards Authorized Representative* Product Enviro Compliance Authorized Representative* Title - Representative Product Enviro Compliance NA Product-Env-Stewards@onsemi.co NA NA Product-Env-Stewards@onsemi.co NA	emi											2024-05-21	-		
Authorized Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Product Enviro Compliance Requester Item Number Representative* Product-Env-Stewards@onsemi.co Requester Item Number Representative* NA Requester Item Number Representative* Product-Env-Stewards@onsemi.co Requester Item Number Representative* NA Requester Item Number Representative* Requester Item Number Requester Item Number Representative* Requester Item Number Requester	Contact Name				Title - Contact			Phone - Contact*				Email - Contact*			
Product Enviro Compliance Requester Item Number Mfr Item Numbe	Product-Env-Stewards				Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM  FDMS86150A FET 100V 4.85 mOhm PQFN56 2024-05-21 PBB 122.136 mg  Manufacturing Proccess Information  Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cyc Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Authorized Representative*			Title - Representative			I	Phone - Representative*				Email - Representative*			
FDMS86150A FET 100V 4.85 mOhm PQFN56 2024-05-21 PBB 122.136 mg    Terminal Plating / Grid Array Material   Terminal Base Alloy   J-STD-020 MSL Rating   Peak Process Body Temperature   Max Time at Peak Temperature   Number of Reflow Cyc   Matte Tin (Sn) - annealed   CU Alloy   1   260   C   30   seconds   3	Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Manufacturing Process Information  Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cyc Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Requester	r Item Number	Mfr Item	Number	per Mfr Item Name			Effective Date	Version	Manufacturing Site		We	ight*	UOM	Unit Type
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cyc Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3			FDMS86	5150A	FET 100V 4.85 mC	Ohm PQFN56		2024-05-21		PBB		122	2.136	mg	Each
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3				Carminal Rasa	Alloy	STD 020 MSI	Dating	Pank Proce	es Rody Tampa	ratura May Ti	ma at Daak '	Tamparatura	Numh	per of Paflow Cyc	lac
	5 -			•		Z Katilig				ille at Feak			bei of Kellow Cyc	ies	
		(Sii) - aimeaieu		Alloy	1			200		30		seconds	13		
wel 1 - maximum time at peak temperature during soldering is 10-30 seconds		me at neak temperatu	uno dunina sol	Idoring is 10.	20 sagands										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belie as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itaability and the Company's remedies for issues that airse regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	19.1	mg	Supplier	Zinc (Zn)	7440-66-6		0.0229	mg
			Supplier	Iron (Fe)	7439-89-6		0.4489	mg
			Supplier	Copper (Cu)	7440-50-8		18.6225	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0057	mg
Die	2.54	mg	Supplier	Silicon (Si)	7440-21-3		2.54	mg
Lead Frame	46.436	mg	Supplier	Silver (Ag)	7440-22-4		0.065	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0464	mg
			Supplier	Iron (Fe)	7439-89-6		0.9752	mg
			Supplier	Copper (Cu)	7440-50-8		45.303	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0464	mg
Mold Compound-Black	42.7	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		2.135	mg
			Supplier	Carbon Black (C)	1333-86-4		0.427	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		38.003	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		2.135	mg
Plating	8.33	mg	Supplier	Tin (Sn)	7440-31-5		8.33	mg
Solder Paste	3.017	mg	Supplier	Silver (Ag)	7440-22-4		0.0754	mg
			A	Lead (Pb)	7439-92-1	7a	2.8812	mg
			Supplier	Tin (Sn)	7440-31-5		0.0603	mg
Wire Bond - Cu	0.013	mg	Supplier	Palladium (Pd)	7440-05-3		0.0002	mg
			Supplier	Gold (Au)	7440-57-5		0	mg
			Supplier	Copper (Cu)	7440-50-8		0.0128	mg